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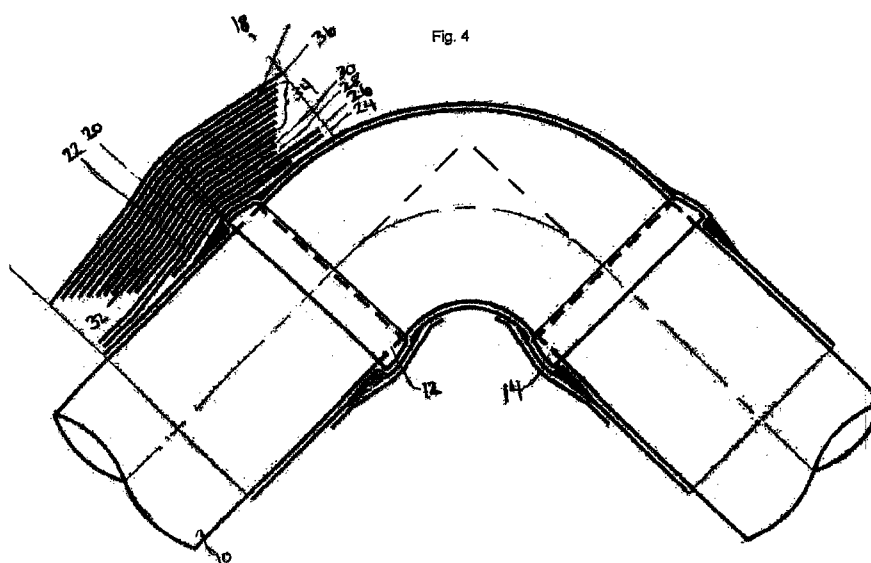
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(54) Title: CARBON FIBER COMPOSITE



(57) Abstract: The present disclosure relates to a composite for sealing a substrate including a primary carbon fiber layer having a first weave density and a secondary carbon fiber layer having a second weave density that is different from the first weave density of the primary carbon fiber layer. Both the primary and secondary carbon fiber layers are encapsulated in a polymer matrix. The disclosure also provides a polymerizable composition and method of sealing a substrate.

